Final Product Change Notification | 201507030F01

Issue Date: 30-Nov-2015
Effective Date: 13-Mar-2016

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Management Summary

Change of bond wire material from Au to Cu, release of 2nd source mold compound, and 2nd source assembly and final test location for dedicated product types in SOT363 package

Change Category

[ ] Wafer Fab process	[ ] Assembly Process	[ ] Product Marking	[ ] Design
[ ] Wafer Fab materials	[X] Assembly Materials	[ ] Electrical spec./Test coverage	[ ] Mechanical Specification
[ ] Wafer Fab location	[X] Assembly Location	[X] Test Location	[ ] Packing/Shipping/Labeling

Change of bond wire from Au to Cu and release of 2nd source assembly location SOT363

Details of this Change

Scheduled changes affect product types in SOT363 (SC-88) package only.

(1) The bond wire material will be changed from gold (Au) to copper (Cu). Gold wire remains qualified for supply security reasons only.
(2) A second source mold compound supplier will be introduced for copper wire products.
(3) Release of NXP Assembly Plant Guangdong (APG), China, as second source of assembly and final test in addition to current location NXP Assembly Plant Seremban (APM), Malaysia.

Old product: wire material is Au (with currently used mold compound suppliers); assembly in APM
Changed product: wire material is Cu (with currently used first and new second source mold compound supplier) or Au (with currently used mold compound suppliers); assembly in APM or APG

The existing processes from APM are copied exactly at APG. Both locations will operate under the same conditions, with same equipment and processes, at equal performance and with comparable systems.

The design and materials of all other components will remain unchanged, i.e. no change of die, die attach, and lead frame. Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Implement this Change
(1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.
(2) Following NXP company policy of second source material availability, a second source mold compound will be added to the BOM. The second source is already a well-established mold compound supplier for NXP GA discrete semiconductor products.
(3) The implementation of the second source assembly center will increase production capacity and flexibility to ensure fulfillment of customer demands.
Identification of Affected Products
Changed products can be identified by date code after implementation.
Assembly location can be tracked by vendor code on package surface and is also stated on packing labels.

Product Availability

Sample Information
Samples are available upon request
Latest sample request date for PCN samples is 31-Dec-2015.
Production
Planned first shipment 01-Apr-2016

Impact

No impact to the products' functionality anticipated.
Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201410006F01	29-Nov-2014	10-Mar-2015	Change of bond wire to copper and release of 2nd mold compound in SOT323 and SOT363
201411005F01	26-Jan-2015	10-May-2015	Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT363
201507030A	16-Aug-2015		Change of bond wire from Au to Cu and release of 2nd source assembly location SOT363

Additional information

Affected products and sales history information: see attached file
Self qualification: view online

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 30-Dec-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:
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Changed Orderable Part#
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BC847BPN,125
BC857BS,135